AMENDMENTS TO THE CLAIMS

Claims 1-17 (Cancelled)

18. (Currently Amended) An apparatus, comprising:

a first device to adjust a polarity associated with a thermoelectric (TEC) module to control a flow of heat, wherein the flow of heat is directed toward a thermal interface material (TIM) to melt the TIM up to an acceptable melt level;

~~a heat sink comprising a thermoelectric (TEC) module having a polarity; and~~

a second device to determine whether the TIM has melted up to the acceptable melt level; and

~~a thermal interface material (TIM)~~ an application device to apply ~~coupled with the heat sink,~~ the TIM ~~receiving a redirected heat in the~~ to a heat sink ~~upon changing of the polarity~~ if the TIM is melted has melted up to the acceptable melt level.

19. (Currently Amended) The apparatus of claim 18, wherein the TIM is applied at ~~and removed from at least one of the following locations:~~ one or more of a base of the heat sink and a thermal gap between the heat sink and a heat source.

20. (Currently Amended) The apparatus of claim 18, wherein the ~~TIM is applied using at least one of the following:~~ application device includes one or more of an epoxy dispenser machine and a vacuum suction cup.

21. (Currently Amended) The apparatus of claim 18, wherein the ~~changing~~ adjusting of the polarity comprises reversing of the polarity.

22. (Currently Amended) The apparatus of claim 21, wherein the ~~reversing~~ adjusting of the polarity ~~is performed by at least of the following:~~ comprises one or more of reversing terminals of the TEC module, ~~using a device to change the polarity of the TEC module,~~ and adjusting a power source.

23. (Currently Amended) A system, comprising:

~~a storage medium;~~

~~a integrated circuit (IC) device coupled with the storage medium;~~

a heat sink coupled with ~~the IC~~ an integrated circuit (IC) device, the heat sink comprising a thermoelectric (TEC) module having a polarity; ~~and~~

a polarity adjustment device to adjust the polarity to direct a flow of heat toward a thermal interface material (TIM) to melt the TIM up to an acceptable melt level;

a device to determine whether the TIM has melted up to the acceptable melt level; and

~~a thermal interface material (TIM)~~ an application device to apply the TIM to ~~coupled with~~ the heat sink ~~and the IC device,~~ if the TIM ~~receiving a redirected heat in the heat sink upon changing of the polarity~~ has melted up to the acceptable melt level.

24. (Currently Amended) The system of claim 23, wherein the TIM is applied ~~at and removed from at least one of the following locations:~~ to one or more of a base of the heat sink and a thermal gap between the heat sink and a heat source.

25. (Currently Amended) The system of claim 23, wherein the ~~TIM is applied using at least one of the following:~~ application device comprises one or more of an epoxy dispenser machine and a vacuum suction cup.

Claims 26-27 (Cancelled)

28. (Currently Amended) The system of claim 23, wherein the IC device comprises ~~at least one of the following:~~ one or more of a microprocessor, a microcontroller, a graphics processor, a digital signal processor (DSP), a complex instruction set computing (CISC) processor, a reduced instruction set computing (RISC) processor, and a very long instruction word (VLIW) processor.